

| | |
|--------------------|----------------|
| V_{DSS} | 30V |
| $R_{DS(on)(Max.)}$ | 17.6m Ω |
| I_D | $\pm 8A$ |
| P_D | 2.0W |

●Features

- 1) Low on - resistance.
- 2) High Power small mold Package (HUML2020L8).
- 3) Pb-free lead plating ; RoHS compliant.
- 4) 100% Rg and UIS tested.
- 5) Halogen Free.

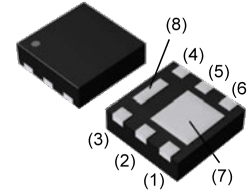
●Application

Switching

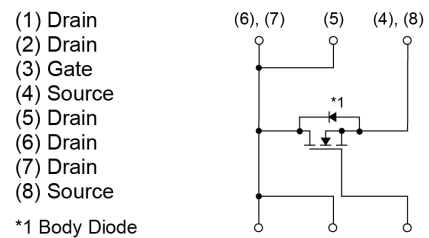
●Outline

DFN2020-8S

HUML2020L8



●Inner circuit



●Packaging specifications

| Type | Packing | Embossed Tape |
|---------------------------|----------------|---------------|
| | Reel size (mm) | 180 |
| Tape width (mm) | 8 | |
| Basic ordering unit (pcs) | 3000 | |
| Taping code | TR | |
| Marking | HB | |

●Absolute maximum ratings ($T_a = 25^\circ C$,unless otherwise specified)

| Parameter | Symbol | Value | Unit |
|--|---------------|-------------|------------|
| Drain - Source voltage | V_{DSS} | 30 | V |
| Continuous drain current | I_D | ± 8 | A |
| Pulsed drain current | I_{DP}^{*1} | ± 32 | A |
| Gate - Source voltage | V_{GSS} | ± 20 | V |
| Avalanche current, single pulse | I_{AS}^{*2} | 2.5 | A |
| Avalanche energy, single pulse | E_{AS}^{*2} | 4.6 | mJ |
| Power dissipation | P_D^{*3} | 2.0 | W |
| Junction temperature | T_j | 150 | $^\circ C$ |
| Operating junction and storage temperature range | T_{stg} | -55 to +150 | $^\circ C$ |

● Thermal resistance

| Parameter | Symbol | Values | | | Unit |
|--|-----------------|--------|------|------|------|
| | | Min. | Typ. | Max. | |
| Thermal resistance, junction - ambient | R_{thJA}^{*3} | - | - | 62.5 | °C/W |

● Electrical characteristics ($T_a = 25^\circ\text{C}$)

| Parameter | Symbol | Conditions | Values | | | Unit |
|--|---|---|--------|------|-----------|---------------|
| | | | Min. | Typ. | Max. | |
| Drain - Source breakdown voltage | $V_{(BR)DSS}$ | $V_{GS} = 0V, I_D = 1mA$ | 30 | - | - | V |
| Breakdown voltage temperature coefficient | $\frac{\Delta V_{(BR)DSS}}{\Delta T_j}$ | $I_D = 1mA$ referenced to 25°C | - | 21 | - | mV/°C |
| Zero gate voltage drain current | I_{DSS} | $V_{DS} = 30V, V_{GS} = 0V$ | - | - | 1 | μA |
| Gate - Source leakage current | I_{GSS} | $V_{GS} = \pm 20V, V_{DS} = 0V$ | - | - | ± 100 | nA |
| Gate threshold voltage | $V_{GS(th)}$ | $V_{DS} = V_{GS}, I_D = 250\mu\text{A}$ | 1.0 | - | 2.0 | V |
| Gate threshold voltage temperature coefficient | $\frac{\Delta V_{GS(th)}}{\Delta T_j}$ | $I_D = 1mA$ referenced to 25°C | - | -3 | - | mV/°C |
| Static drain - source on - state resistance | $R_{DS(on)}^{*4}$ | $V_{GS} = 10V, I_D = 8A$ | - | 13.5 | 17.6 | m Ω |
| | | $V_{GS} = 4.5V, I_D = 8A$ | - | 18.9 | 24.6 | |
| Gate resistance | R_G | f=1MHz, open drain | - | 2.8 | - | Ω |
| Forward Transfer Admittance | $ Y_{fs} ^{*4}$ | $V_{DS} = 5V, I_D = 8A$ | 5 | - | - | S |

*1 $P_w \leq 10\mu\text{s}$, Duty cycle $\leq 1\%$

*2 $L \approx 1\text{mH}$, $V_{DD} = 15V$, $R_G = 25\Omega$, Starting $T_j = 25^\circ\text{C}$ Fig.3-1,3-2

*3 Mounted on a Cu Board (40×40×0.8mm)

*4 Pulsed

● Electrical characteristics ($T_a = 25^\circ\text{C}$)

| Parameter | Symbol | Conditions | Values | | | Unit |
|------------------------------|-------------------|------------------------------------|--------|------|------|------|
| | | | Min. | Typ. | Max. | |
| Input capacitance | C_{iss} | $V_{GS} = 0V$ | - | 660 | - | pF |
| Output capacitance | C_{oss} | $V_{DS} = 15V$ | - | 90 | - | |
| Reverse transfer capacitance | C_{rss} | $f = 1\text{MHz}$ | - | 75 | - | |
| Turn - on delay time | $t_{d(on)}^{*4}$ | $V_{DD} \approx 15V, V_{GS} = 10V$ | - | 8 | - | ns |
| Rise time | t_r^{*4} | $I_D = 4A$ | - | 10 | - | |
| Turn - off delay time | $t_{d(off)}^{*4}$ | $R_L \approx 3.75\Omega$ | - | 33 | - | |
| Fall time | t_f^{*4} | $R_G = 10\Omega$ | - | 7 | - | |

● Gate charge characteristics ($T_a = 25^\circ\text{C}$)

| Parameter | Symbol | Conditions | Values | | | Unit | |
|----------------------|---------------|------------------------------------|-----------------|------|------|------|----|
| | | | Min. | Typ. | Max. | | |
| Total gate charge | Q_g^{*4} | $V_{DD} \approx 15V$ $I_D = 8A$ | $V_{GS} = 10V$ | - | 14.5 | - | nC |
| Gate - Source charge | Q_{gs}^{*4} | | $V_{GS} = 4.5V$ | - | 7.2 | - | |
| Gate - Drain charge | Q_{gd}^{*4} | | $V_{GS} = 4.5V$ | - | 2.7 | - | |
| | | | | - | 2.4 | - | |

● Body diode electrical characteristics (Source-Drain) ($T_a = 25^\circ\text{C}$)

| Parameter | Symbol | Conditions | Values | | | Unit |
|----------------------------|---------------|----------------------------|--------|------|------|------|
| | | | Min. | Typ. | Max. | |
| Continuous forward current | I_S | $T_a = 25^\circ\text{C}$ | - | - | 1.67 | A |
| Pulse forward current | I_{SP}^{*1} | | - | - | 32 | A |
| Forward voltage | V_{SD}^{*4} | $V_{GS} = 0V, I_S = 1.67A$ | - | - | 1.2 | V |

● Electrical characteristic curves

Fig.1 Power Dissipation Derating Curve

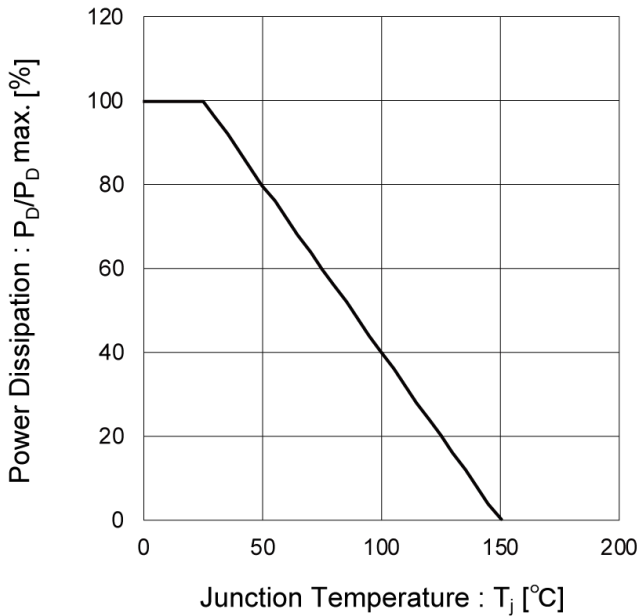


Fig.2 Maximum Safe Operating Area

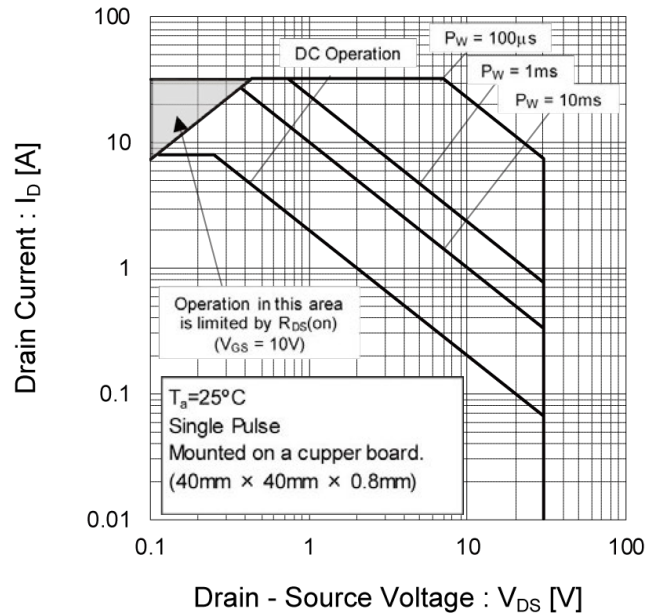


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

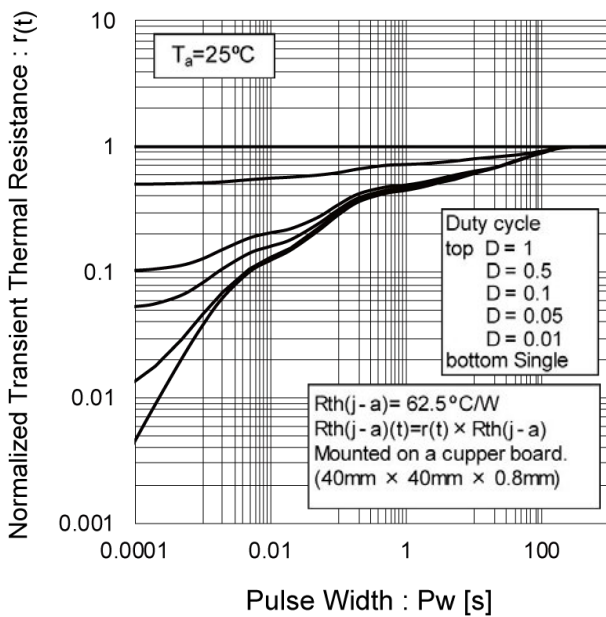
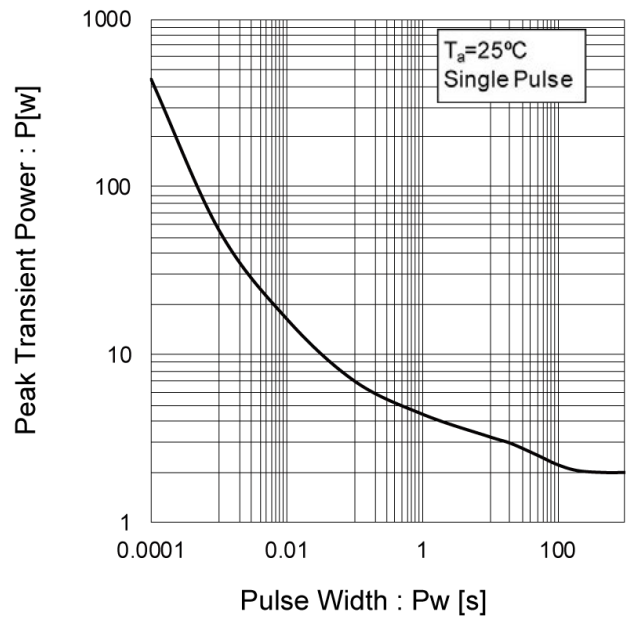


Fig.4 Single Pulse Maximum Power dissipation



● Electrical characteristic curves

Fig.5 Typical Output Characteristics(I)

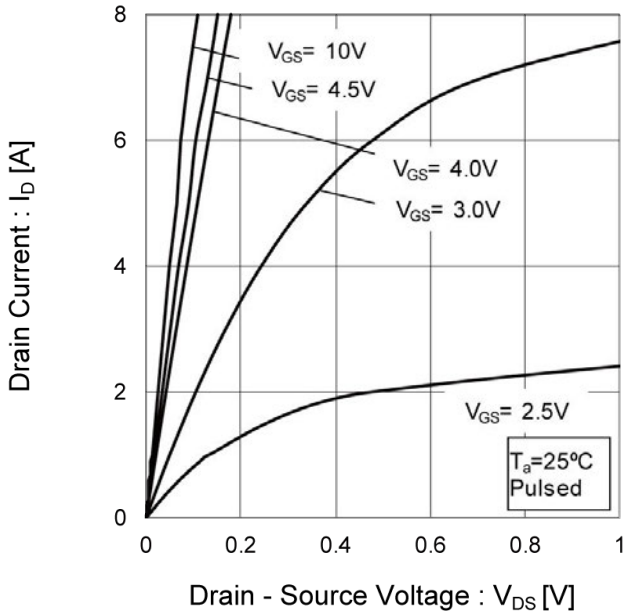


Fig.6 Typical Output Characteristics(II)

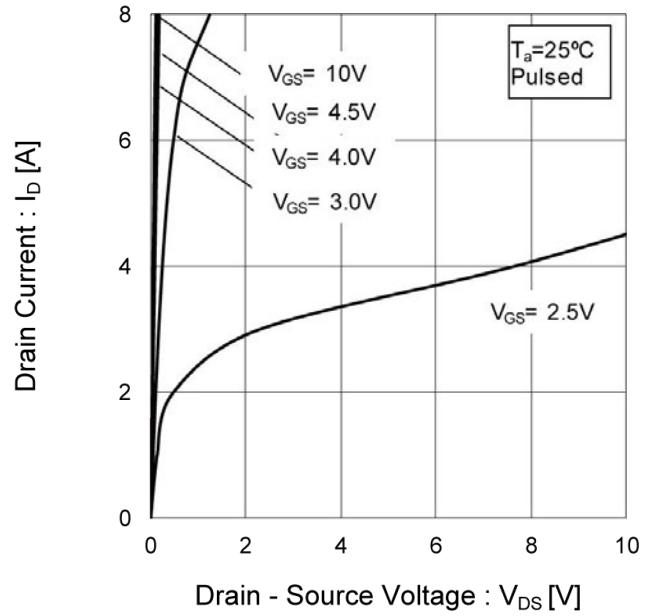


Fig.7 Breakdown Voltage vs. Junction Temperature

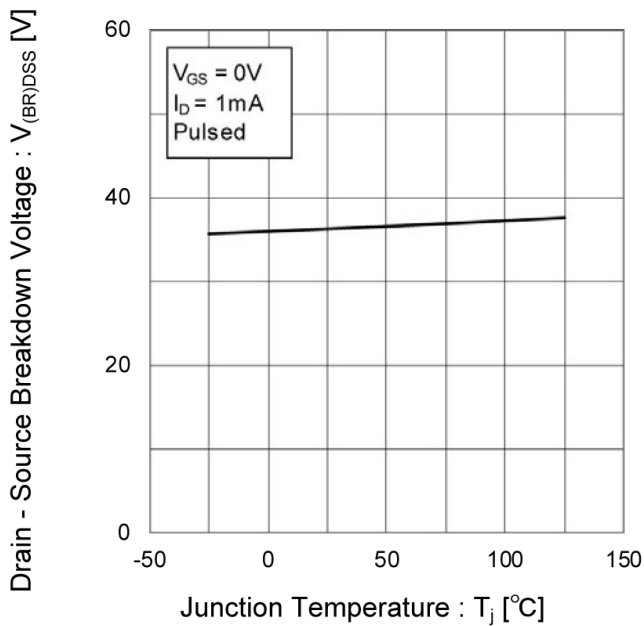
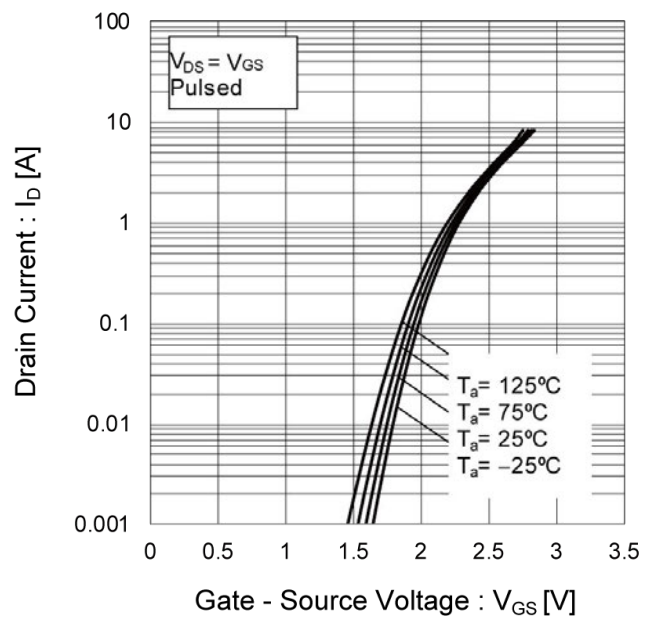


Fig.8 Typical Transfer Characteristics



● Electrical characteristic curves

Fig.9 Gate Threshold Voltage vs. Junction Temperature

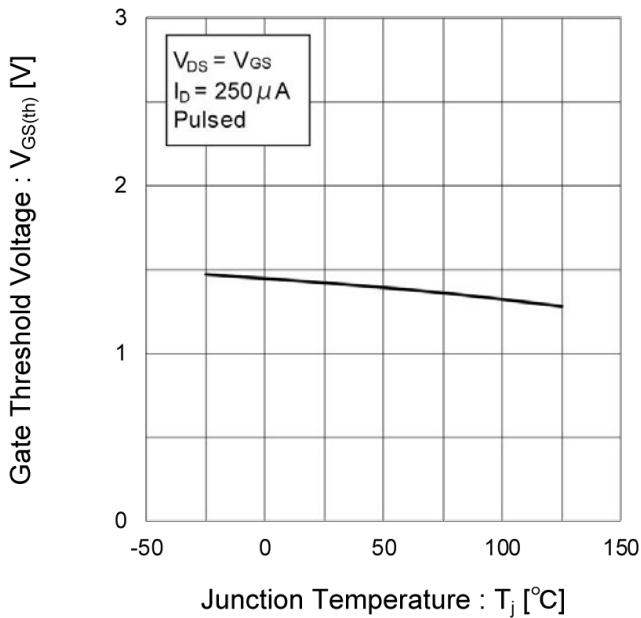


Fig.10 Forward Transfer Admittance vs. Drain Current

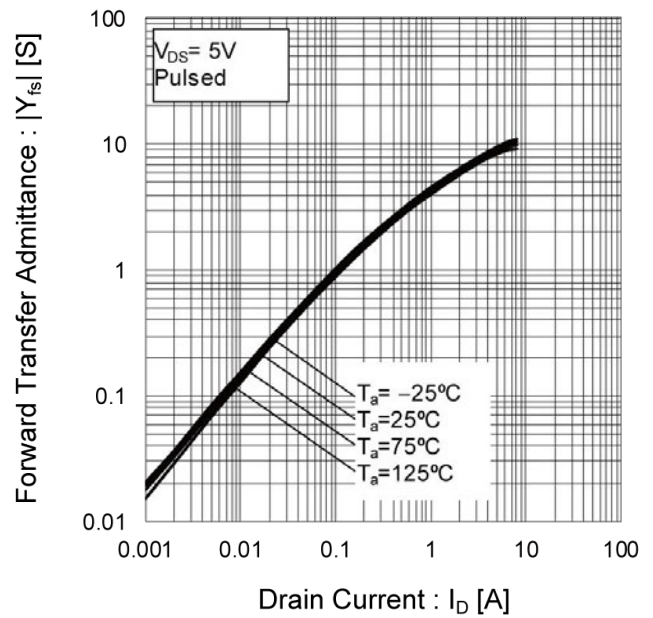


Fig.11 Drain Current Derating Curve

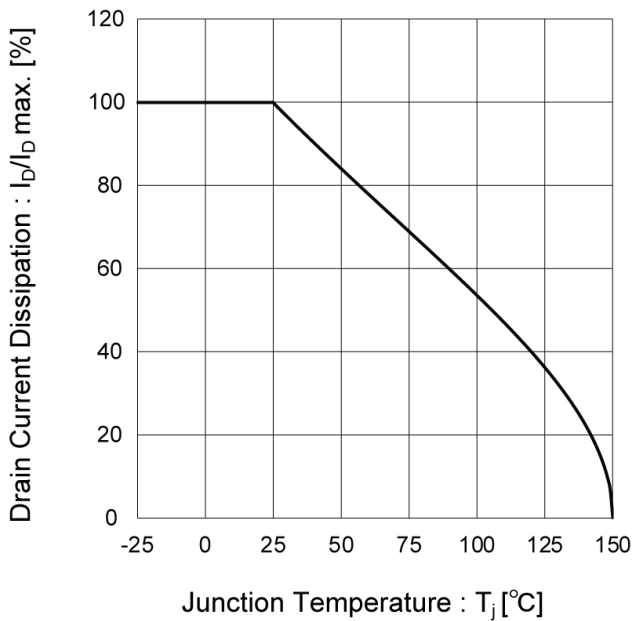
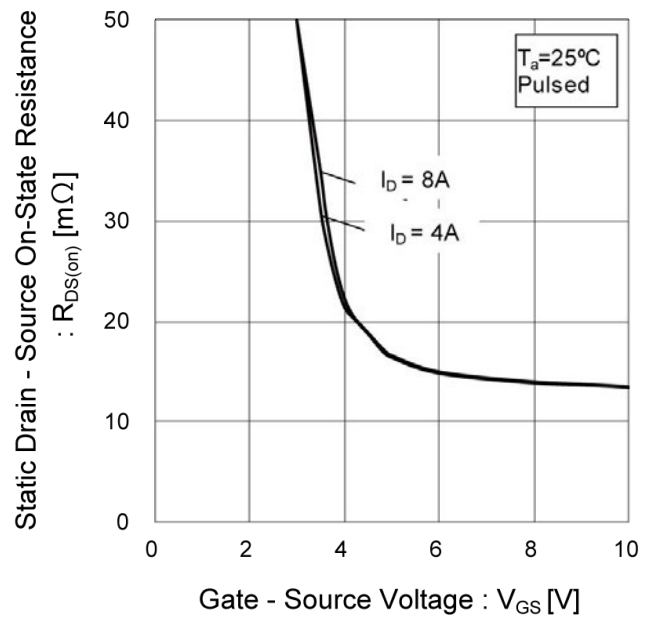


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage



● Electrical characteristic curves

Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature

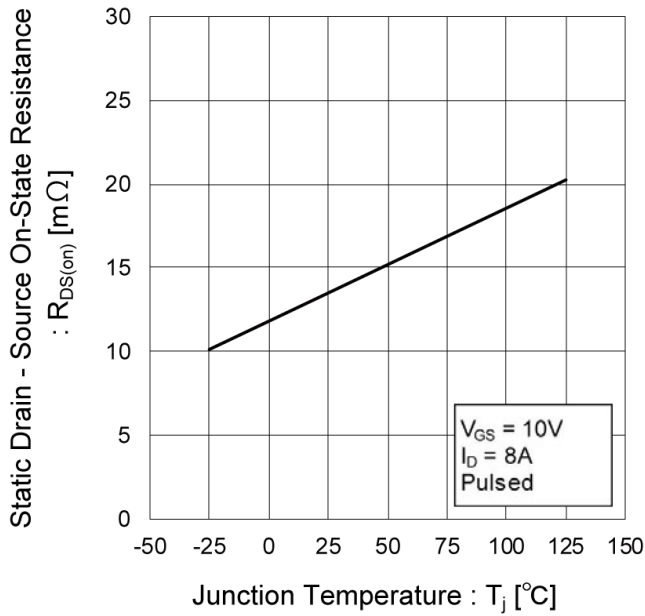


Fig.14 Static Drain - Source On - State Resistance vs. Drain Current (I)

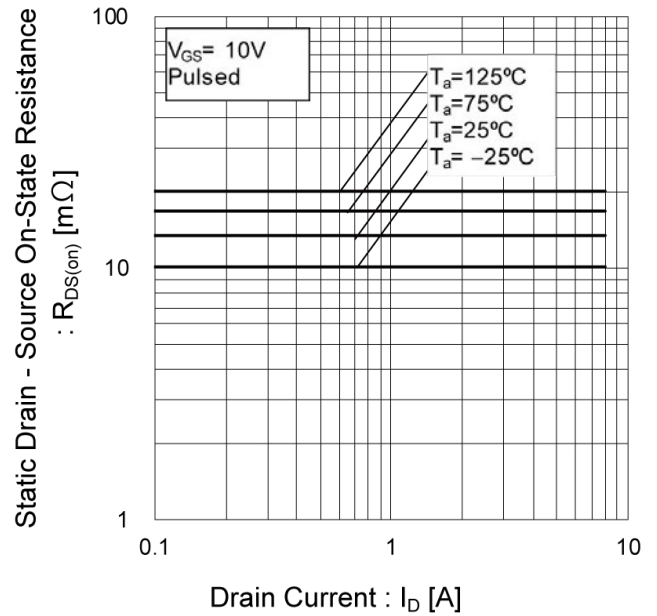
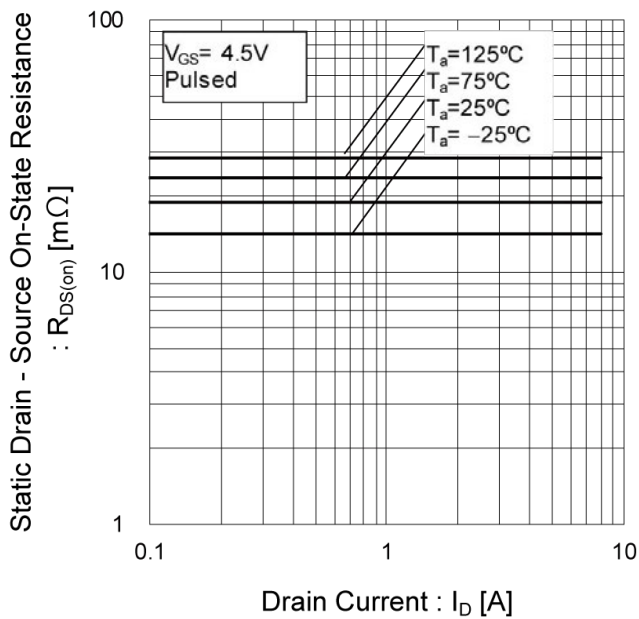


Fig.15 Static Drain - Source On - State Resistance vs. Drain Current (II)



●Electrical characteristic curves

Fig.16 Typical Capacitance vs. Drain - Source Voltage

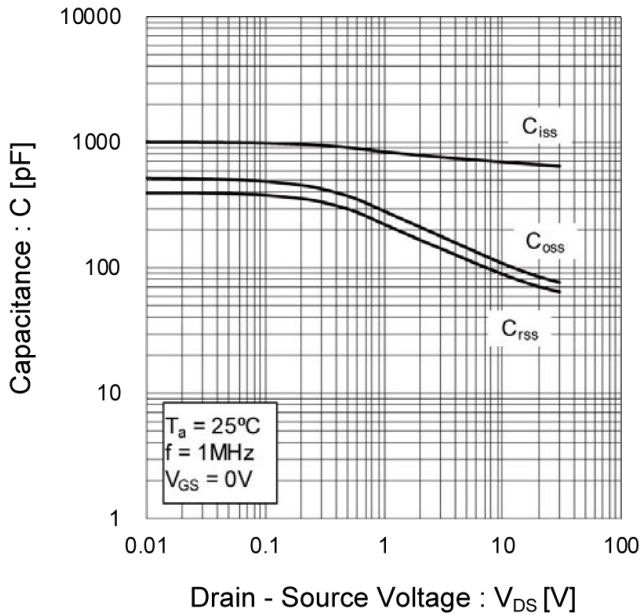


Fig.17 Switching Characteristics

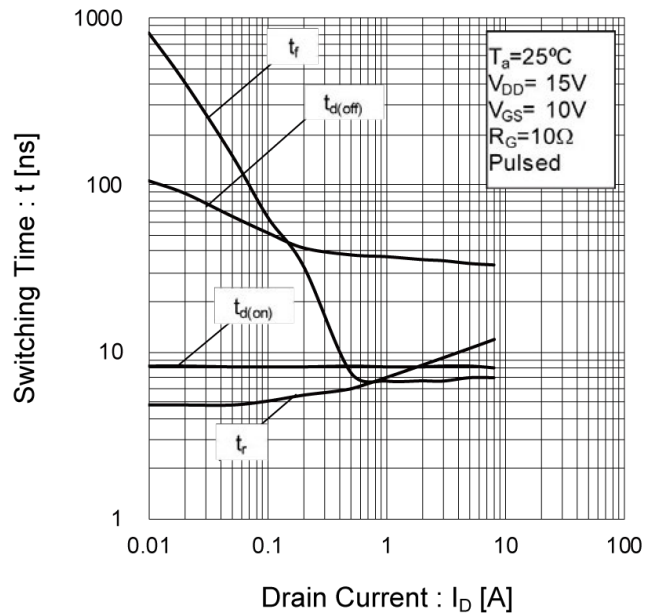


Fig.18 Dynamic Input Characteristics

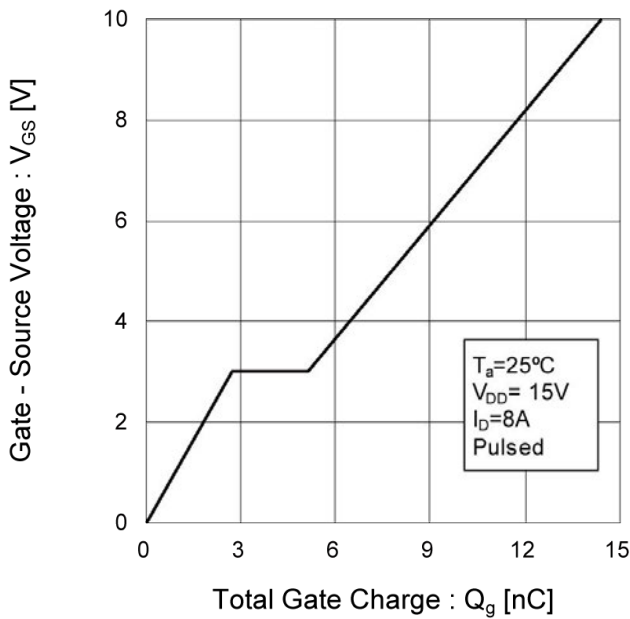
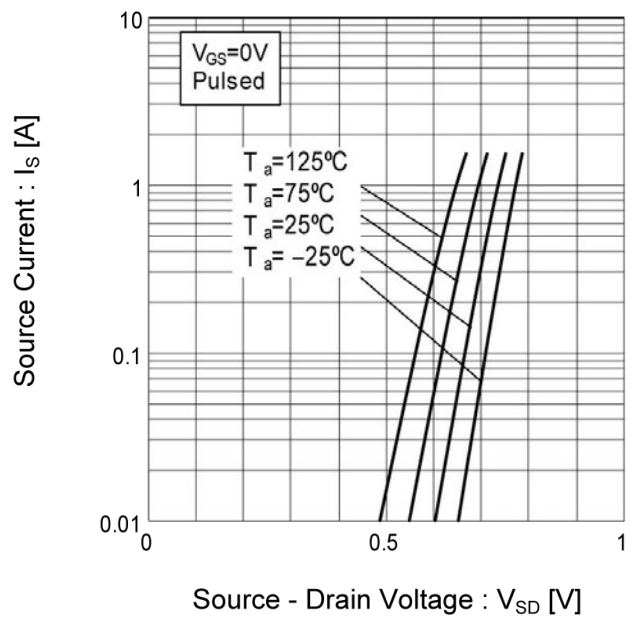


Fig.19 Source Current vs. Source Drain Voltage



● Measurement circuits

Fig.1-1 Switching Time Measurement Circuit



Fig.1-2 Switching Waveforms



Fig.2-1 Gate Charge Measurement Circuit



Fig.2-2 Gate Charge Waveform

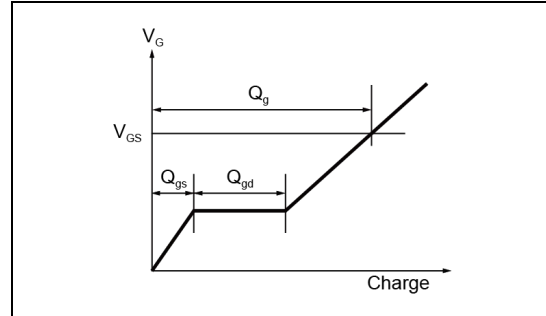


Fig.3-1 Avalanche Measurement Circuit



Fig.3-2 Avalanche Waveform

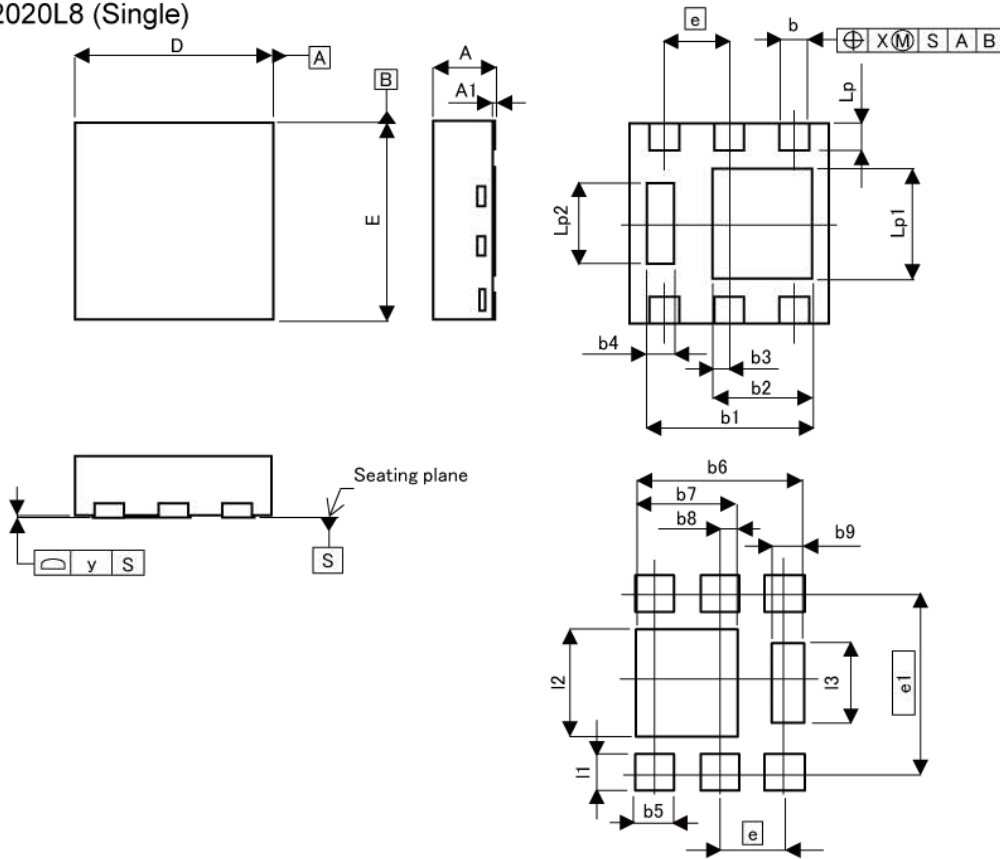


● Notice

This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit.

●Dimensions

DFN2020-8S
 HUML2020L8 (Single)



Pattern of terminal position areas
 [Not a pattern of soldering pads]

| DIM | MILIMETERS | | INCHES | |
|-----|------------|-------|--------|-------|
| | MIN | MAX | MIN | MAX |
| A | 0.55 | 0.65 | 0.022 | 0.026 |
| A1 | 0.00 | 0.05 | 0.000 | 0.002 |
| b | 0.25 | 0.35 | 0.010 | 0.014 |
| b1 | 1.55 | 1.75 | 0.061 | 0.069 |
| b2 | 0.95 | 1.05 | 0.037 | 0.041 |
| b3 | 0.175 | | 0.007 | |
| b4 | 0.25 | | 0.010 | |
| D | 1.90 | 2.10 | 0.075 | 0.083 |
| E | 1.90 | 2.10 | 0.075 | 0.083 |
| e | 0.60 | 0.70 | 0.024 | 0.028 |
| Lp | 0.225 | 0.325 | 0.009 | 0.013 |
| Lp1 | 1.00 | 1.20 | 0.039 | 0.047 |
| Lp2 | 0.80 | | 0.031 | |
| x | - | 0.10 | - | 0.004 |
| y | - | 0.10 | - | 0.004 |

| DIM | MILIMETERS | | INCHES | |
|-----|------------|-------|--------|-------|
| | MIN | MAX | MIN | MAX |
| b5 | - | 0.45 | - | 0.018 |
| b6 | - | 1.75 | - | 0.069 |
| b7 | - | 1.05 | - | 0.041 |
| b8 | 0.175 | | 0.007 | |
| b9 | - | 0.30 | - | 0.012 |
| e1 | 1.725 | | 0.068 | |
| l1 | - | 0.425 | - | 0.017 |
| l2 | - | 1.15 | - | 0.045 |
| l3 | - | 0.85 | - | 0.033 |

Dimension in mm/inches

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|-----------|-----------|------------|-----------|
| CLASS III | CLASS III | CLASS II b | CLASS III |
| CLASS IV | | CLASS III | |

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 - Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
 - Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - Sealing or coating our Products with resin or other coating materials
 - Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - Use of the Products in places subject to dew condensation
- The Products are not subject to radiation-proof design.
- Please verify and confirm characteristics of the final or mounted products in using the Products.
- In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of ionizer, friction prevention and temperature / humidity control).

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1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
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 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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